NUV 2 2 2005

RESPONSE UNDER 37 CFR 1.116 EXPEDITED PROCEDURE EXAMINING GROUP 2814

> PATENT APPLICATION Docket No.: 9903-074 Client Ref. No.: S03US003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Dong-Ho LEE

Serial No.:

10/750,979

Examiner:

Le, Thao X.

Filed:

January 2, 2004

Group Art Unit:

2814

Confirmation No.:

5476

For:

Please Do Hot Enter

STACK PACKAGE MADE OF CHIP SCALE PACKAGES

Mail Stop AF Commissioner for Patents P.O. Box 1450

Alexandria, VA 22313-1450

AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR 1.116

Responsive to the Final Office Action, Paper No. 091605, dated September 22, 2005, please amend the application as follows.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.